202009US-2 DIV Docket No.

IN RE APPLICATION OF: Shigenobu MAEDA

SERIAL NO: 09/761,738

FILED:

January 18, 2001

FOR:

FEB 13 2002 SUCTOR MANUFACTURING... MANUFACTURING METHOD OF SEMICONDUCTOR WAFER, SEMICON

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ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

- No additional fee is required
- Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- Additional documents filed herewith:

Marked-Up Copy

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	4	MINUS	20	0	× \$18 =	\$0.00
INDEPENDENT	1	MINUS	3	0	× \$84 =	\$0.00
		□ MULTIPLE DEPENDENT CLAIMS + \$280 =				\$0.00
			TOTAL OF A	BOVE CALCU	JLATIONS	\$0.00
□ Reduction by 50% for filing by Small Entity				tity	\$0.00	
		□ Recore	dation of Assignment	t	+ \$40 =	\$0.00
	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1				TOTAL	\$0.00

A check in the amount of

is attached.

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

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7/ Suppl. Amot C 2.25.02

202009US-2DIV

FEB 1 2 2002 B

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IN THE UNITED STATES PATENT & TRADEMARK TOFFICEGY CENTER 2800

IN RE APPLICATION OF

:

SHIGENOBU MAEDA

: EXAMINER: PYONIN, A.

SERIAL NO: 09/761,738

FILED: JANUARY 18, 2001

: GROUP ART UNIT: 2824

FOR: MANUFACTURING METHOD OF:

SEMICONDUCTOR WAFER,

SEMICONDUCTOR MANUFACTURING APPARATUS, AND SEMICONDUCTOR

DEVICE

SUPPLEMENTAL AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Responsive to the Official Action mailed October 24, 2001 and supplemental to the Amendment filed January 24, 2002, please amend the above-identified patent application as follows:

IN THE CLAIMS

Please amend Claim 22 as follows:

by DI

22. (Twice Amended) The method of manufacturing a semiconductor device

according to Claim 21, wherein

said each mask pattern of said plural intellectual properties has a mark for positioning,

and

positioning of said mask patterns is performed by superposing one of said marks on another of said marks.